

L Number	Hits	Search Text	DB	Time stamp
1	258	438/758.ccls. and hydrogen	USPAT; US-PGPUB	2004/09/23 10:02
2	20	(438/758.ccls. and hydrogen) and plat\$3 and nickel	USPAT; US-PGPUB	2004/09/23 10:01
3	1	438/761.ccls. and hydrogen and nickel with bath	USPAT; US-PGPUB	2004/09/23 10:02
-	592162	hydrogen or "h.sub.2"	USPAT; US-PGPUB	2004/09/23 10:00
-	1814	(hydrogen or "h.sub.2") adj saturat\$4	USPAT; US-PGPUB	2004/08/26 16:05
-	866	((hydrogen or "h.sub.2") adj saturat\$4) and plat\$4	USPAT; US-PGPUB	2004/08/26 14:53
-	66	((((hydrogen or "h.sub.2") adj saturat\$4) and plat\$4) and semiconductor	USPAT; US-PGPUB	2004/08/26 15:47
-	12609	electroless adj plat\$4	USPAT; US-PGPUB	2004/09/13 15:57
-	272	(electroless adj plat\$4) near6 semiconduct\$3	USPAT; US-PGPUB	2004/08/26 15:15
-	0	((electroless adj plat\$4) near6 semiconduct\$3) and nickle near4 bath	USPAT; US-PGPUB	2004/08/26 15:15
-	0	((electroless adj plat\$4) near6 semiconduct\$3) and nickal near4 bath	USPAT; US-PGPUB	2004/08/26 15:15
-	25	((electroless adj plat\$4) near6 semiconduct\$3) and nickel near4 bath	USPAT; US-PGPUB	2004/08/26 15:15
-	14	((((electroless adj plat\$4) near6 semiconduct\$3) and nickel near4 bath) and (hydrogen or "h.sub.2")	USPAT; US-PGPUB	2004/09/16 09:11
-	4	(((((hydrogen or "h.sub.2") adj saturat\$4) and plat\$4) and semiconductor) and nickel near6 bath	USPAT; US-PGPUB	2004/08/26 15:47
-	16	(hydrogen adj saturation) and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:17
-	2	2001/0035452	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/26 16:16
-	4	2001/0033020	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/26 16:19
-	173	hydrogen adj saturation	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/27 15:49
-	45	hydrogen adj saturation and plat\$6 near6 nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:07

-	9	hydrogen near3 saturat\$4 and plat\$6 near5 nickel near4 bath	USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT	2004/08/27 16:09
-	2	("4789452" "4877508").PN.	USPAT	2004/08/27 16:08
-	3	4877508.URPN.	USPAT	2004/08/27 16:08
-	18	hydrogen near3 saturat\$4 and nickel near4 bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/27 16:13
-	50	hydrogen with saturat\$4 and nickel near4 bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/10 11:22
-	434	427/438.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/10 11:22
-	64	427/438.ccls. and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/10 11:38
-	56	"3403035"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/10 12:00
-	38	3403035.URPN.	USPAT	2004/09/10 11:40
-	700	438/678.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:42
-	120	438/678.ccls. and nickel near6 plating	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 09:17
-	42	copper adj coat\$3 near2 \$wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:42
-	912902	hydrogen or "h.sub.2"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 15:58
-	1445	(hydrogen or "h.sub.2") and 427/43\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 15:59
-	831	(hydrogen or "h.sub.2") and 427/43\$.ccls. and plat\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 16:00

-	33	(hydrogen or "h.sub.2") and 427/43\$.ccls. and plat\$3 with (nickel adj bath)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 16:10
-	4	nickel adj bath and dummy adj (metal plat\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 16:08
-	0	427/98.ccls.	USPAT; US-PGPUB	2004/09/14 09:49
-	899	427/405.ccls.	USPAT; US-PGPUB	2004/09/13 16:17
-	26	427/405.ccls. and nickel adj bath	USPAT; US-PGPUB	2004/09/13 16:18
-	626	427/436.ccls.	USPAT; US-PGPUB	2004/09/13 16:18
-	12	427/436.ccls. and nickel adj bath	USPAT; US-PGPUB	2004/09/14 09:16
-	1523	(copper Cu) adj (coat\$3 layer film) near2 (semiconductor or conductor \$wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 16:20
-	35	((copper Cu) adj (coat\$3 layer film) near2 (semiconductor or conductor \$wafer)) with (nickel or Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/13 16:21
-	13	427/436.ccls. and nickel adj bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 09:11
-	111	427/43\$.ccls. and nickel adj bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/14 09:38
-	70	427/43\$.ccls. and copper adj plate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/14 09:38
-	446	427/98.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/14 09:49
-	0	427/98.ccls. and nickel adj bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/14 09:49
-	64	427/98.ccls. and (nickel or Ni)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/14 09:50
-	14	((electroless adj plat\$4) near6 semiconduct\$3) and nickel near4 bath) and (hydrogen or "h.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 09:12

-	159	427/436.ccls. and nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 09:17
-	87	(((electroless adj plat\$4) near6 semiconduct\$3) and nickel) and (hydrogen or "h.sub.2")	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 09:12
-	60	427/436.ccls. and nickel and hydrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/16 09:17
-	5	hydrogen adj saturation and nickel adj bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:08
-	3	hydrogen adj saturation with plat\$3 near3 nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:08
-	0	(hydrogen adj saturation) and 438/687.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:17
-	516	hydrogen and 438/687.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:18
-	3	hydrogenation and 438/687.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:37
-	12726	saturated near2 hydrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:37
-	30	saturated near2 hydrogen with nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:40
-	48	saturat\$4 near2 hydrogen with nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:42
-	20	(saturat\$4 near2 hydrogen with nickel) not (saturated near2 hydrogen with nickel)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:41
-	1	saturat\$4 near2 hydrogen and 438/687.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:43

-	5	saturat\$4 near2 hydrogen with copper with nickel	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:55
-	1376	427/304.ccls. or 427/305.ccls. and nickel adj bath	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:56
-	349	(427/304.ccls. or 427/305.ccls. and nickel adj bath) and hydrogen	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:56
-	298	((427/304.ccls. or 427/305.ccls. and nickel adj bath) and hydrogen) and copper	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:56
-	1	(427/304.ccls. or 427/305.ccls. and nickel adj bath) and hydrogen adj (saturation or saturated)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:57
-	15	(427/304.ccls. or 427/305.ccls. and nickel adj bath) and (hydrogen adj (saturation or saturated) or hydrogenation)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/09/21 14:57